

**Thermoplastic
road repair system**

Hot applied surface defect repair system

Fast and innovative solution

ChipFill® is a specially designed thermoplastic for repairing cracks and smaller holes with diameter around 15-20 cm, and minimizing the risk of defects getting bigger.

The repairing time is about 20 minutes from start to opening for traffic.

Handling of ChipFill® is easy

The hot applied thermoplastic gives better bonding to the underground compared to cold applied repair systems. When heated, the binders in the thermoplastic bond to the bitumen in the asphalt.

ChipFill® is a temporary solution that keeps the cost down by avoiding water from going into the underground and making the holes/cracks and damages bigger.

When working with ChipFill®, there is no need for big bulky machinery. You can simply have it on your vehicle, and easily repair smaller defects as you see them.

ChipFill® can be applied all year round

ChipFill® is easy to use and apply. Use a stiff brush to clean the hole/crack, and preheat the area with a propane gas burner. Fill in a layer of ChipFill® maximum 15 mm, and heat the material with the gas burner. The heated ChipFill® will start to be fluent and follow the contexture of the hole.

If the hole/crack is deeper than 15 mm, then let the layer set before applying a further layer on top of the first one. The maximum hole hole should not exceed 45 mm.

To secure initial skid resistance and to avoid ghost markings, post sprinkle anti-skid aggregates after application while the material is still hot.



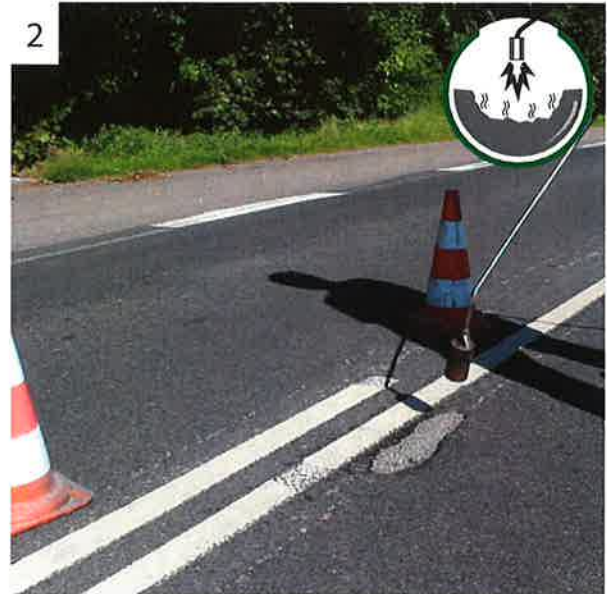
"ChipFill® is easy to use and apply"



Application in four easy steps:



Thoroughly brush away any dirt and remove moisture from the hole/crack with a gas burner



Preheat the whole area with a gas burner



Apply ChipFill® in a thin layer and spread out (maximum 15 mm thick)



Heat the material with a gas burner - and finish by sprinkling anti-skid aggregates on the hot material

No waste, no mess, no problem

ChipFill® consists of small chips which makes it extremely easy to work with. Simply pour on the material where needed and sweep up the excess material to save it for later use. This means no waste, but also no mess as you can easily sweep unwanted chips off the surface before applying heat with the gas burner leaving no marks on the actual cobblestones.



Alternative usage of ChipFill®

 **ChipFill®** PREMARK® applied on cobblestones with ChipFill® and Viaxi®:



Clean the joints/cracks and preheat the surface with a gas burner. The depth of the joints must not exceed 45 mm.

Apply a layer of ChipFill® (of maximum 15 mm thickness).

Heat the ChipFill® until it becomes black, fluent and follows the contexture of the joints. Repeat this step as needed until the joints are filled.

Consumption: One bag of 12 kg covers an area of 0.4 m² when applied in a layer of 15 mm thickness, i.e. 40 metres of joints of 10 mm width and 15 mm depth on average.

Viaxi® is a very effective two-component primer which is specially developed for concrete surfaces, cobblestones, and tiles. Expected coverage is approx. 200 ml/m², i.e. 220g/m².



Tube 380 ml



Bucket 3.5 kg

GEVEKO MARKINGS

ChipFill® is made in Denmark by Geveko Markings Denmark A/S
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ChipFill®



1

Thoroughly brush away any dirt and remove moisture from the pothole/crack with a gas burner



2

Apply ChipFill® in a thin layer and spread out (maximum 15 mm thick)



3

Heat ChipFill® through thoroughly to melt the material



4

Apply another thin layer if necessary. Finish by sprinkling anti-skid aggregates on the hot material

GEVEKO MARKINGS

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MY ChipFill® Application Manual

GENERAL REQUIREMENTS

Surface:

- **ChipFill®** is compatible with all asphalt surfaces.
- **ChipFill®** should not be used for repairing non-bituminous surfaces without using a recommended primer (e.g. concrete, bricks and cobble stones).
- The surface must be horizontal with only little slope, maximum 5%.
- The surface must be totally dry before installation! Remove all moisture from the application area using the gas burner.
- The surface must be free of dirt, dust, chemicals and oily substances. Remove these by using a broom or compressed air.

Storage and Handling:

- **ChipFill®** material must always be kept dry – in storage, in transit and on the job.
- **ChipFill®** must be stored at maximum 30°C.
- **ChipFill®** packages must be stored flat and stacked max. 10 packs high.
- Shelf life is 12 months from production date.

Safety precautions:

Protective clothing (leather boots/work shoes and long trousers) should be worn whilst applying **ChipFill®**. NOTE: No synthetic fabrics should be worn.

The person(s) making the installation should, if possible, always have the back up against the wind so that the gas burner flame is kept away from the body.



APPLICATION

1. Clean application area thoroughly by removing all sand, dirt, chemicals and oily substances. Use a broom or compressed air to clean the surface.
2. Pre-heat the affected area with the gas burner to ensure that all moist is removed.
3. If **ChipFill®** is used to repair a non-bituminous surface (e.g. concrete or cobble stone area) use the recommended primer and follow the instruction for the primer. **Important.** The primer should not be applied on top of **ChipFill®**.
4. If **ChipFill®** is compressed, then the bags can be dropped to the ground to separate the chips/pellets. Drop height maximum 50 cm.
5. Fill in a layer of **ChipFill®** of maximum 15 mm, and heat the material to above 200°C with the gas burner. Keep 20-40 cm distance to the surface of material. Use a slow even sweeping motion ensuring not to scorch and damage the material. The heated **ChipFill®** will start to be fluent and follow the contexture of the hole.
 - a. If the hole is extending 15 mm in depth repeat point 4. Make sure all materials are liquid before adding a new layer of **ChipFill®**. The maximum hole or joint depth should not exceed 50 mm.
6. Ensure all material is melted and above 200°C.
7. To secure initial skid resistance and avoid ghost marking, post-sprinkle anti-skid aggregates after application, while the material is still hot.
8. Once **ChipFill®** is cooled, check with a gloved hand to ensure the surface is firm before opening the road to traffic and check that the anti-skid aggregates are providing a textured finish and is firmly bonded.
 - a. Water can be applied to accelerate cooling.
9. Reopening for traffic is normally after 5-10 minutes all depending of hole depth and temperature.

ChipFill® in combination with PREMARK®/DecoMark®/ViaTherm®

Follow the instruction above. No primer should be used on top of **ChipFill®**, but if the surface around the area of repair needs sealer, it need to be installed after the application of **ChipFill®** in order not to "flash".

The use of primer on top of **ChipFill®** can lead to weakening of **ChipFill®** and/or **PREMARK®**.

PRODUCT TRAINING

All end-users of **ChipFill®** have the possibility to receive authorized guidance or product training free of charge. For first-time users of **ChipFill®** this is highly recommended! Please contact your **ChipFill®** supplier or Geveko Markings for further information.

Product name: ChipFill®
Colour: Black
Material class: Hot applied surface defect repair system
Certificate:

Technical Data sheet
Version 2018.1
Type:

Intended usage

Temporary repairing of potholes with a maximum depth of 5 cm and maximum diameter of 20 cm and natural crack and joints. ChipFill® can be applied all year around, at low temperature extra heating is needed.

Product description

Alkyd based thermoplastic material that is capable of conforming to ground contours and geometries. The material can be applied at temperatures down to 10°C, below this temperature extra care must be taken when handling for both storage and application. ChipFill® is made so it set rapidly, permitting the access route to be re-opened to traffic 20 minutes after application.

Approx. 20% binding agent

Approx. 50% Aggregate filler

Approx. 30% Filler

System recommendation

The material is recommended for temporary repair of bitumen rich surfaces. For Portland concrete, use a recommended Primer from Geveko Markings. See installation instructions for the primer before use. For filling joints around cobble stones see separate installation instruction.

Application and equipment recommendations

Conventional gas torch with post sprinkling of drop on friction material.

Application temperature: Heat up the material to 200-230°C

For further information, please refer to the ChipFill® Application Instructions

Set-up time / Hardening time

10 minutes at a surface temperature of 20°C and a light breeze

Packaging

ChipFill® is delivered in bags of 12kg

Delivered as full pallets; 66 bags (792kg)

Storage, handling and safety

ChipFill® should be stored at temperatures below 32°C.

Don't stack the pallets on top of each other.

Environment and health

Contains none of the substance which is either on the Candidate List of substances of very high concern, or recommended for inclusion in Annex XIV or Annex XIV / XVII under REACH regulation (EC 1207/2006).

For further information, please refer to the ChipFill® MSDS

Performance according to EN 1790 – Road marking materials - Preformed road markings

Characteristic	Requirement
Skid resistance (SRT)	S3 (>55 SRT/PTV)

